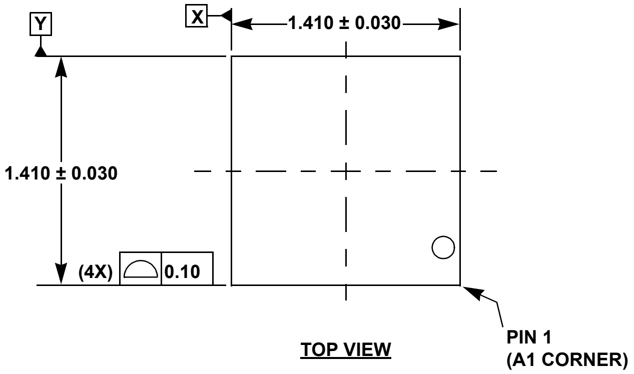
Package Outline Drawing

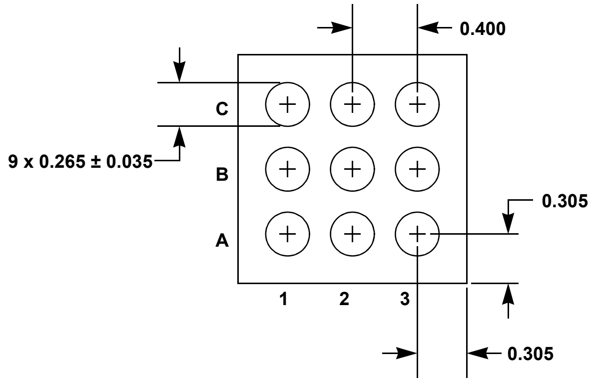
W3x3.9D

3x3 ARRAY 9 BALLS WITH 0.40 PITCH WAFER LEVEL CHIP SCALE PACKAGE (WITH BSC)

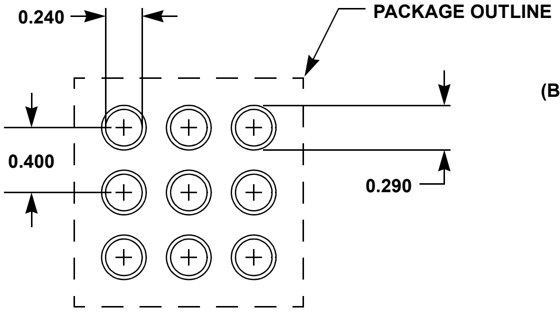
Rev 0, 1/14



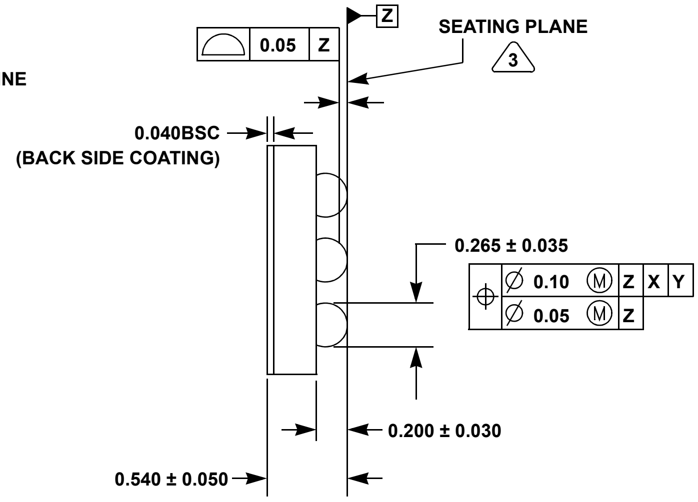
TOP VIEW



BOTTOM VIEW



RECOMMENDED LAND PATTERN



SIDE VIEW

NOTES:

1. All dimensions are in millimeters.
2. Dimension and tolerance per ASMEY 14.5 - 1994, and JESD 95-1 SPP-010.
3. NSMD refers to Non-Solder Mask Defined pad design per Intersil Tech Brief TB451 located at: http://www.intersil.com/content/dam/Intersil/documents/tb45/tb451.pdf